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Product Update: Finix Ball Mounter, Model FX300

Finix Technology, the technology and Equipment arm of Rokko Holdings Ltd, today announces that it has begun shipment and mass production of its proprietary and revolutionary solder ball placement system, designated the FX300* .



FX300* patent pending

A New Era in Packaging Technology

The Ball Grid Array (BGA) package is known for its ability to maintain signal integrity in high I/O count applications. These packages are used in the manufacture of memory, logic, graphic and communication chips. Fast throughput and high density ICs are today's market trend.

Extensive R&D has led to the development of key proprietary technologies that have increased manufacturing throughput to an unprecedented level without compromising on the fine pitch and high ball count capabilities required by the solder ball placement process.

FX300 uses its very own proprietary RY dual WIP technology to bring about a compact and highly synchronized system. Together with an optimized process station layout and careful component selection, this key technical innovation has delivered an incredible increase in UPH, and therefore, has contributed to a substantial reduction in the Cost of Ownership for the user.



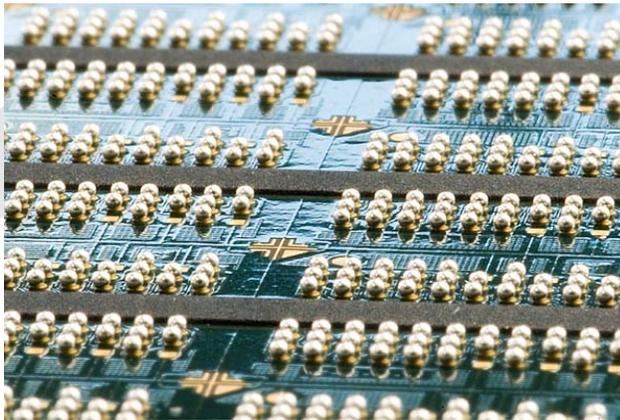
The Innovative Approach

Every key aspect of the solder ball placement process has been carefully scrutinized during the development of the FX300.

The flux and solder ball pick and place position is recipe based, attributable to its dedicated X, Y, Z and theta axes designed on each of its robotic arms. Together with real time pneumatic control, the high rigidity robotic arms are capable of placing fine pitch and high ball count applications.

Traditional technology uses 2 steps approach (via the robotic arm) to locate the substrate for flux and ball placement. Their vision positioning accuracy is therefore dependant on the positioning capability and vibration dynamics of the robot. The FX300 however, it able to locate in 1 step, due to its dedicated vision system design. Vibration dynamics is virtually non-existent and this translates to improved placement accuracy.

Significant advancement was made in the area of lighting and imaging for the FX300, used in both the fiducial station and the After-Mount-Inspection (AMI) station. The specially designed lighting is copper pad and organic substrate ‘ready’, which is known to be difficult to detect due to oxidation and low light contrast.



Meanwhile, the AMI has the true capability of distinguishing diametrical differences in the solder balls to prevent ‘mixed up’ solder ball sizes in the package, a feature much sought after in the industry.

The FX300 can handle packages of substrate form and singulated units (via Auer boat). The machine can handle sizes of up to 260x85 (mm) in size with an effective placement area of 250x74 (mm).

About Finix Technology

Finix Technology, the technology and Equipment arm of Rokko Holdings Ltd, provides process automation solutions for the semiconductor packaging industry. Please visit our website at www.rokkogroup.com or contact our sales personnel at sales@rokko.net for more details.